



RECEIVED
AMENDED VERSION OF SECTION OF SPECIFICATION

DEC 26 2001
TC 2800 MAY 2001

Applicants respectfully request the substitution of the table below for the table appearing at the bottom of page 9 and at the top of page 10 of the description of this application as filed.

CI

Application Number	Title of Application	First Named Inventor
09/687,787	Thin and Heat Radiant Semiconductor Package and Method for Manufacturing	Jae Hun Ku
09/687,331	Leadframe for Semiconductor Package and Mold for Molding the Same	Young Suk Chung
09/687,532	Method for Making a Semiconductor Package Having Improved Defect Testing and Increased Production Yield	Tae Heon Lee
09/687,876	Near Chip Size Semiconductor Package	Sean Timothy Crowley
09/687,536	End Grid Array Semiconductor Package	Jae Hun Ku
09/687,585	Semiconductor Package Having Reduced Thickness	Tae Heon Lee
09/687,541	Semiconductor Package Leadframe Assembly and Method of Manufacture	Young Suk Chung
09/687,049	Method for Making Semiconductor Packages	Young Suk Chung

Replacement sheets 9-10 of the specification are enclosed for the convenience of the Examiner in entering the preceding amendment.